(spring near5 (polymer or (plastice or organic))) (spring near5 (polymer or (plastice or organic))) (spring near5 (polymer or (plastice or organic))) (SP-GPUB, EPO: JPO: DERWENT: IBM TDB USPAT: US-PGPUB, EPO: JPO: DERWENT: IBM TDB USPAT: US-PGPUB; EPO: JPO: DERWENT: IBM TDB USPAT: U	L Number	Hits	Search Text	DB	Time stamp
1445 (257/719,722), CCLS. C57/719,722), CCLS. C57/719, C57/719, CCLS. C57/719, C57/719, CCLS. C57/719, CCLS. C57/719, CCLS. C57/719, CCLS.	3	1	((((257/718).CCLS.) and (ic or integrated)) and spring) and	USPAT;	2002/07/11 16:32
1445 (257/719,722).CCLS.			(spring near5 (polymer or (plastice or organic)))		
1445 257/719,722).CCLS. IBM_TDB USPAT; US-PG-PUB; EFO; JPO; DERWENT; IBM_TDB USPAT; US-PG-PUB; EFO; JPO; DERW					
1445 (257/719,722).CCLS. USPAT;					
Section Sect	4	1445	(257/719.722).CCLS.		2002/07/11 16:32
5 563 ((257/719,722).CCLS.) and (ic or integrated)					2002/07/11 10:52
DERWENT: IBM TDB USPAT: US-PGPUB; EPO; JPO; DERWENT: IBM TDB U					
563 ((257/719,722).CCLS.) and (ic or integrated) USPAT: US-PGPUB: EPO: JPO: DERWENT: IBM TDB USPAT: US-P					
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1	5	563	((257/719,722).CCLS.) and (ic or integrated)		2002/07/11 16:51
DERWENT: Same polymer) DERWENT: DERWENT: Same polymer) DERWENT: DERWENT: Same polymer) DERWENT:					
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Same polymer Same polymer US-PGPUB; EPC; JPC; Dec JPC; Dec JPC; Dec JPC; Dec JPC; JPC; Dec JPC; Dec JPC; JPC	6	1	(((257/719 722) CCLS) and (ic or integrated)) and (spring		2002/07/11 16:34
7 166 (ic or "integrated circuit") and (spring same polymer) 8 17 ((ic or "integrated circuit") and (spring same polymer)) and (heat near4 (sink or spreder)) 9 13 (((ic or "integrated circuit") and (spring same polymer)) and (heat near4 (sink or spreder)) 10 5104 (257/678,706,712,713,717).CCLS.) 11 2078 (((257/678,706,712,713,717).CCLS.) and (ic or integrated)) 12 1 ((((257/678,706,712,713,717).CCLS.) and (ic or integrated)) 13 405 (((257/678,706,712,713,717).CCLS.) and spring) 14 242 ((((257/678,706,712,713,717).CCLS.) and spring) and (ic or integrated)) 15 16 (((257/678,706,712,713,717).CCLS.) and spring) and (ic or integrated) 16 (((257/678,706,712,713,717).CCLS.) and spring) 17 18 19 19 10 (((257/678,706,712,713,717).CCLS.) and spring) 18 10 2002/07/11 10 (((257/678,706,712,713,717).CCLS.) and spring) 19 10 11 ((((257/678,706,712,713,717).CCLS.) and spring) 10 11 2078 ((((257/678,706,712,713,717).CCLS.) and spring) 11 2078 ((((257/678,706,712,713,717).CCLS.) and spring) 12 10 11 ((((257/678,706,712,713,717).CCLS.) and spring) 13 2002/07/11 11 (((257/678,706,712,713,717).CCLS.) and spring) 14 24 ((((257/678,706,712,713,717).CCLS.) and spring) and (ic or integrated)) 15 16 ((((257/678,706,712,713,717).CCLS.) and spring) and (ic or integrated)		•			2002/07/11 10.34
The content of the			James polymoly		
166 (ic or "integrated circuit") and (spring same polymer) IBM_TDB USPAT; US-PGPUB; EPC; JPC; DERWENT; ISM_TDB USPAT; US-PGPUB; EPC; JPC; DERWENT; ISM				DERWENT:	
166 (ic or "integrated circuit") and (spring same polymer) USPAT; US-PGPUB; EPO, JPO; DERWENT; IBM, TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM, TDB USPAT; US-PGPUB; EPO, JPO; DERWENT; IBM, TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM, TDB U	1				
8 17 ((ic or "integrated circuit") and (spring same polymer)) and (heat near4 (sink or spreder)) 9 13 (((ic or "integrated circuit") and (spring same polymer)) and (heat near4 (sink or spreder))) not eldridge 10 5104 (257/678,706,712,713,717).CCLS. 11 2078 ((257/678,706,712,713,717).CCLS.) and (ic or integrated) 12 1 (((257/678,706,712,713,717).CCLS.) and (ic or integrated)) 13 405 ((257/678,706,712,713,717).CCLS.) and spring 14 242 (((257/678,706,712,713,717).CCLS.) and spring) 15 2002/07/11 1 16 202/07/11 1 17 2078 ((257/678,706,712,713,717).CCLS.) and spring 18 2002/07/11 1	7	166	(ic or "integrated circuit") and (spring same polymer)	USPAT;	2002/07/11 16:52
17 ((ic or "integrated circuit") and (spring same polymer)) and (heat near4 (sink or spreder)) USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGP					
8 17 ((ic or "integrated circuit") and (spring same polymer)) and (heat near4 (sink or spreder)) 9 13 (((ic or "integrated circuit") and (spring same polymer)) and (heat near4 (sink or spreder))) not eldridge 10 5104 (257/678,706,712,713,717).CCLS. 11 2078 ((257/678,706,712,713,717).CCLS.) and (ic or integrated) 12 1 (((257/678,706,712,713,717).CCLS.) and (ic or integrated)) 13 405 (((257/678,706,712,713,717).CCLS.) and spring 14 242 ((((257/678,706,712,713,717).CCLS.) and spring) 15 16 17 ((((257/678,706,712,713,717).CCLS.) and spring) and (ic or integrated)) 17 (((((257/678,706,712,713,717).CCLS.) and spring) and (ic or integrated)) 18 19 10 17 ((((257/678,706,712,713,717).CCLS.) and spring) 19 18 19 19 10 19					
8 17 ((ic or "integrated circuit") and (spring same polymer)) and (heat near4 (sink or spreder)) USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB 2002/07/11 1 9 13 (((ic or "integrated circuit") and (spring same polymer)) and (heat near4 (sink or spreder))) not eldridge USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB 2002/07/11 1 10 5104 (257/678,706,712,713,717).CCLS.) USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB 2002/07/11 1 11 2078 ((257/678,706,712,713,717).CCLS.) and (ic or integrated) USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB 2002/07/11 1 12 1 (((257/678,706,712,713,717).CCLS.) and spring) USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB 2002/07/11 1 13 405 (((257/678,706,712,713,717).CCLS.) and spring) USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB 2002/07/11 1 14 242 ((((257/678,706,712,713,717).CCLS.) and spring) and (ic or integrated) US-PGPUB; US-PGPUB; US-PGPUB;					
13	8	17	((ic or "integrated circuit") and (spring same polymer)) and		2002/07/11 16:41
9 13 (((ic or "integrated circuit") and (spring same polymer)) and (heat near4 (sink or spreder))) not eldridge 10 5104 (257/678,706,712,713,717).CCLS. 11 2078 ((257/678,706,712,713,717).CCLS.) and (ic or integrated) 12 1 (((257/678,706,712,713,717).CCLS.) and (ic or integrated)) 13 405 ((257/678,706,712,713,717).CCLS.) and spring 14 242 (((257/678,706,712,713,717).CCLS.) and spring) and (ic or integrated) 15 EPC, JPC; DERWENT; IBM_TDB USPAT; US-PGPUB; EPC; JPC; DERWENT; IBM_TDB USPAT; US-PGPUB	•				2002/07/11 10.41
9 13 (((ic or "integrated circuit") and (spring same polymer)) and (heat near4 (sink or spreder))) not eldridge 10 5104 (257/678,706,712,713,717).CCLS. 11 2078 ((257/678,706,712,713,717).CCLS.) and (ic or integrated) 12 1 (((257/678,706,712,713,717).CCLS.) and (ic or integrated)) 13 405 ((257/678,706,712,713,717).CCLS.) and spring 14 242 (((257/678,706,712,713,717).CCLS.) and spring) 15 DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	1		(macrisal r (shint or oprodory)		
9					
(heat near4 (sink or spreder))) not eldridge US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB					
EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; US-P	9	13			2002/07/11 16:48
DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	-		(heat near4 (sink or spreder))) not eldridge		
10 5104 (257/678,706,712,713,717).CCLS. IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; ISM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; ISM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; ISM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; ISM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; ISM_TDB USPAT; US-PGPUB; USPAT; US-PGPUB; USPAT; US-PGPUB; USPAT; US-PGPUB; USPAT; US-PGPUB;					
10 5104 (257/678,706,712,713,717).CCLS. 11 2078 ((257/678,706,712,713,717).CCLS.) and (ic or integrated) 12 1 (((257/678,706,712,713,717).CCLS.) and (ic or integrated)) 13 405 ((257/678,706,712,713,717).CCLS.) and spring 14 242 (((257/678,706,712,713,717).CCLS.) and spring) 2002/07/11 1 2002/07/11 1 2002/07/11 1 2002/07/11 1 2002/07/11 1 2002/07/11 1 2002/07/11 1					
US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; US-PGPUB; US-PGPUB; US-PGPUB; US-PGPUB;	10	5104	(257/678 706 712 713 717) CCLS		2002/07/11 17:32
11 2078 ((257/678,706,712,713,717).CCLS.) and (ic or integrated) EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; US-P		0101	(2077010,1700,1712,170,1717).0020.	1	2002/07/11 17:02
11 2078 ((257/678,706,712,713,717).CCLS.) and (ic or integrated) DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; USPAT;					
11 2078 (((257/678,706,712,713,717).CCLS.) and (ic or integrated) 12 1 ((((257/678,706,712,713,717).CCLS.) and (ic or integrated)) 13 405 (((257/678,706,712,713,717).CCLS.) and spring 14 242 ((((257/678,706,712,713,717).CCLS.) and spring) and (ic or integrated) 15 USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; US-PGPUB; Integrated)	ŀ				
12 1 (((257/678,706,712,713,717).CCLS.) and (ic or integrated))		±			
12 1 (((257/678,706,712,713,717).CCLS.) and (ic or integrated)) and (spring same polymer) 13 405 (((257/678,706,712,713,717).CCLS.) and spring 14 242 ((((257/678,706,712,713,717).CCLS.) and spring) and (ic or integrated) EPO; JPO; DERWENT; IBM_TDB US-PGPUB; IBM_TDB US-PGPUB; INTEGRATED US-PGPUB; IN	11	2078	((257/678,706,712,713,717).CCLS.) and (ic or integrated)		2002/07/11 16:53
12 1 (((257/678,706,712,713,717).CCLS.) and (ic or integrated)) and (spring same polymer) 13 405 (((257/678,706,712,713,717).CCLS.) and spring 14 242 ((((257/678,706,712,713,717).CCLS.) and spring) and (ic or integrated) DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB					
12 1 (((257/678,706,712,713,717).CCLS.) and (ic or integrated)) and (spring same polymer) IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; ISM_TDB USPAT; US-PGPUB; ISM_TDB USPAT; US-PGPUB; INTEGRATED USPAT;					
12 1 (((257/678,706,712,713,717).CCLS.) and (ic or integrated)) and (spring same polymer) USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; IBM_TDB USPAT; US-PGPUB; IBM_TDB USPAT; US-PGPUB; INTEGRATED USPAT;					
and (spring same polymer) US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; IBM_TDB USPAT; US-PGPUB; IBM_TDB USPAT; US-PGPUB; INtegrated)	12	1	(((257/678,706,712,713.717).CCLS.) and (ic or integrated))		2002/07/11 16:52
13 405 (((257/678,706,712,713,717).CCLS.) and spring EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US		•		US-PGPUB;	
13 405 (((257/678,706,712,713,717).CCLS.) and spring IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; INtegrated) 2002/07/11 1				EPO; JPO;	
13 405 ((257/678,706,712,713,717).CCLS.) and spring USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; USPA					
US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; Integrated) 242 (((257/678,706,712,713,717).CCLS.) and spring) and (ic or integrated) US-PGPUB;	40	405	((057/070 700 740 740 747) OOLO \ dd		2002/07/44 46:50
EPO; JPO; DERWENT; IBM_TDB USPAT; integrated) 242 (((257/678,706,712,713,717).CCLS.) and spring) and (ic or integrated) 2002/07/11 1	13	405	((257/678,706,712,713,717).CCLS.) and spring		2002/07/11 16:53
DERWENT; IBM_TDB USPAT; INTEGRATED USPAT; US-PGPUB;					
14 242 (((257/678,706,712,713,717).CCLS.) and spring) and (ic or integrated) IBM_TDB USPAT; US-PGPUB;					
14 242 (((257/678,706,712,713,717).CCLS.) and spring) and (ic or integrated) USPAT; US-PGPUB; 2002/07/11 1				,	
integrated) US-PGPUB;	14	242	(((257/678,706,712,713,717).CCLS.) and spring) and (ic or	_	2002/07/11 16:54
				US-PGPUB;	
				EPO; JPO;	
DERWENT;					
IBM_TDB 1/4/07/07/07/07/07/07/07/07/07/07/07/07/07/	45		///057/070 700 740 740 747 001 0 \ - \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	IBM_TDB	2002/07/44 47:44
	15	56			2002/07/11 17:14
integrated)) and (spring same (polymer or (plastic or (organic or flexible)))) US-PGPUB; EPO; JPO;					
DERWENT;	-		OF HEADING////		
IBM_TDB					

40	-1 20000			
16	20026	cantilever and spring	USPAT;	2002/07/11 17:14
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
17	10141	(cantilever and spring) and (cantilever same spring)	USPAT;	2002/07/11 17:15
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
18	5752	((cantilever and spring) and (cantilever same spring)) and	USPAT;	2002/07/11 17:16
		(cantilever near4 spring)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
19	2729	(((cantilever and spring) and (cantilever same spring)) and	USPAT;	2002/07/11 17:16
		(cantilever near4 spring)) and "cantilever spring"	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	:
			IBM_TDB	
20	71	((((cantilever and spring) and (cantilever same spring)) and	USPAT;	2002/07/11 17:17
		(cantilever near4 spring)) and "cantilever spring") and (ic or	US-PGPUB;	
		"integrated chip")	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
21	1	((257/678,706,712,713,717).CCLS.) and "cantilever spring"	USPAT;	2002/07/11 17:34
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
22	4	((257/719,722).CCLS.) and "cantilever spring"	USPAT;	2002/07/11 17:36
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
23	0	(((((257/718).CCLS.) and (ic or integrated)) and spring) and	USPAT;	2002/07/11 17:36
		(spring near5 (polymer or (plastice or organic)))) and	US-PGPUB;	
		"cantilever spring"	EPO; JPO;	
			DERWENT;	
			IBM TDB	